

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

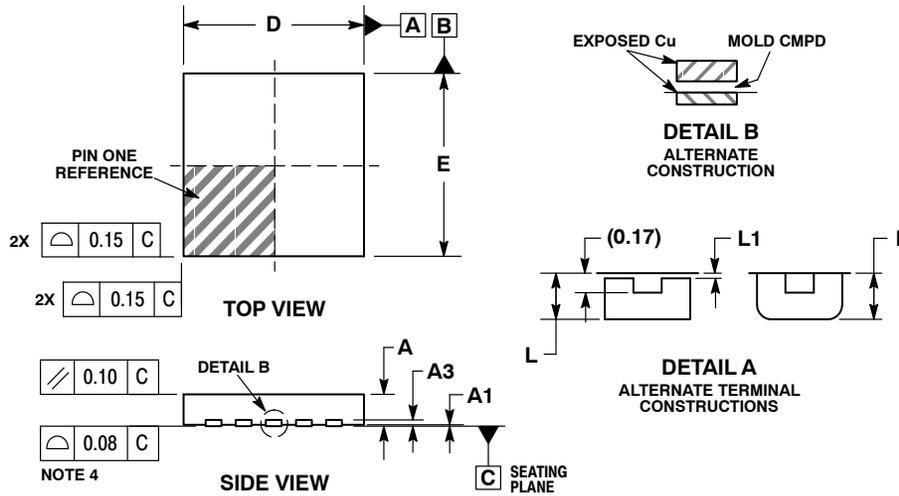


SCALE 2:1

UDFN10 3x3, 0.5P (Leads 2 & 3 Tied)

CASE 517CC
ISSUE 0

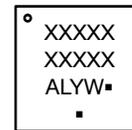
DATE 10 OCT 2011



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETERS.
 - DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 - COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	3.00 BSC	
D2	2.39	2.59
E	3.00 BSC	
E2	1.59	1.79
e	0.50 BSC	
L	0.35	0.45
L1	---	0.15

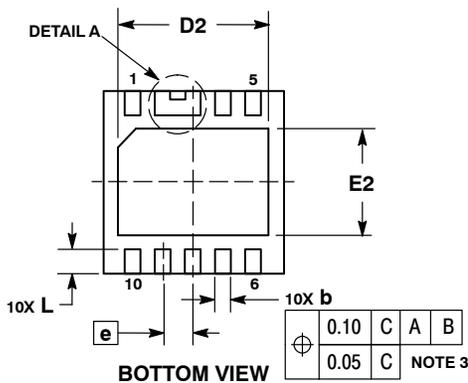
GENERIC MARKING DIAGRAM*



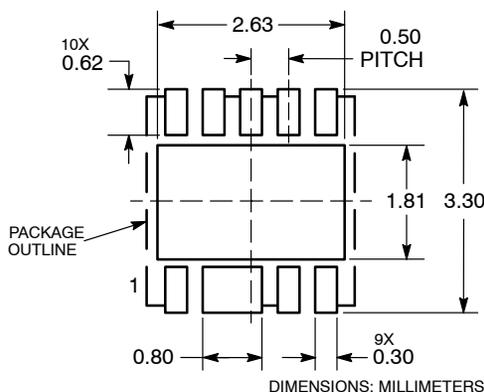
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN10 3X3, 0.5P (LEADS 2 & 3 TIED)	PAGE 1 OF 2

